Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**ANODE**

**.025 x .25”**

**.041”**

**.041”**

**Top Material: Al**

**Backside Material: TiNiAg**

**Bond Pad Size: .025” X .025”**

**Backside Potential: Cathode**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .041” X .041” DATE: 9/1/21**

**MFG: SENSITRON THICKNESS .010” P/N: 1N4944**

**DG 10.1.2**

#### Rev B, 7/19/02